



Material Content Data Sheet



Sales Product Name		TLE42694E		Issued		28. August 2013		
MA#		MA000969726						
Package		PG-SSOP-14-2		Weight*		83.37 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.391	2.87	2.87	28678	28678
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8265	
wire	non noble metal	copper	7440-50-8	27.978	33.56	34.44	335577	344358
	noble metal	gold	7440-57-5	0.278	0.33	0.33	3339	3339
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1178
plastics	plastics	epoxy resin	-	4.516	5.42		54167	
		inorganic material	silicondioxide	60676-86-0	44.473	53.33	58.87	533430
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11708	11708
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9207	9207
glue	plastics	epoxy resin	-	0.290	0.35		3484	
		noble metal	silver	7440-22-4	0.871	1.05	1.40	10451
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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